BT149 series

### **GENERAL DESCRIPTION**

### **QUICK REFERENCE DATA**

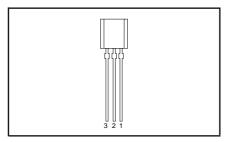
Passivated, sensitive gate thyristors in a plastic envelope, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
$V_{\text{DRM}}, V_{\text{RRM}}$	BT149 Repetitive peak off-state voltages Average on-state	<b>B</b> 200	<b>D</b> 400 0.5	<b>G</b> 600	V A
I <sub>T(RMS)</sub> I <sub>TSM</sub>	current RMS on-state current Non-repetitive peak on-state current	0.8 8	0.8 8	0.8	A A

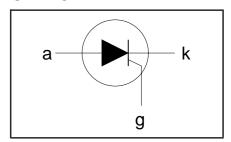
## **PINNING - TO92 variant**

PIN	DESCRIPTION			
1	cathode			
2	gate			
3	anode			

## **PIN CONFIGURATION**



# **SYMBOL**



## **LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
$V_{DRM}$ , $V_{RRM}$	Repetitive peak off-state voltages		-	<b>B</b> 200 <sup>1</sup>	<b>D</b> 400 <sup>1</sup>	<b>G</b> 600 <sup>1</sup>	V
I <sub>T(AV)</sub>	Average on-state current	half sine wave;	-		0.5		A
I <sub>T(RMS)</sub> I <sub>TSM</sub>	RMS on-state current Non-repetitive peak on-state current	$T_{lead} \le 83 ^{\circ}\text{C}$ all conduction angles t = 10 ms t = 8.3 ms half sine wave; $T_i = 25 ^{\circ}\text{C}$ prior to surge	- - -		0.8 8 9		A A A
l <sup>2</sup> t dl <sub>T</sub> /dt	l²t for fusing Repetitive rate of rise of on-state current after	$I_{TM} = 2 \text{ A}; I_{G} = 10 \text{ mA}; \\ I_{TM} = 2 \text{ A}; I_{G} = 10 \text{ mA}; \\ dI_{G}/dt = 100 \text{ mA/}\mu\text{s}$	- -		0.32 50		A²s A/μs
I <sub>GM</sub> V <sub>GM</sub> V <sub>RGM</sub> P <sub>GM</sub> P <sub>G(AV)</sub> T <sub>stg</sub> T <sub>j</sub>	triggering Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- - - - -40 -		1 5 5 2 0.1 150 125		۵°, ۵°, ۵°,

<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ $\mu$ s.

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# THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-lead</sub>	Thermal resistance junction to lead		-	-	60	K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient	pcb mounted; lead length = 4mm	-	150	-	K/W

# STATIC CHARACTERISTICS

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>GT</sub> I <sub>L</sub> I <sub>H</sub>	Gate trigger current Latching current Holding current On-state voltage	$V_D$ = 12 V; $I_T$ = 10 mA; gate open circuit $V_D$ = 12 V; $I_{GT}$ = 0.5 mA; $R_{GK}$ = 1 k $\Omega$ $V_D$ = 12 V; $I_{GT}$ = 0.5 mA; $R_{GK}$ = 1 k $\Omega$	- - -	50 2 2 1.2	200 6 5 1.35	μΑ mA mA V
$V_{T}$	Gate trigger voltage	$I_T = 1 \text{ A}$ $V_D = 12 \text{ V}$ ; $I_T = 10 \text{ mA}$ ; gate open circuit $V_D = V_{DRM(max)}$ ; $I_T = 10 \text{ mA}$ ; $T_j = 125 \text{ °C}$ ;	0.2	0.5 0.3	0.8	V V
I <sub>D</sub> , I <sub>R</sub>	Off-state leakage current	gate open circuit $V_D = V_{DRM(max)}$ ; $V_R = V_{RRM(max)}$ ; $T_j = 125$ °C; $R_{GK} = 1 \text{ k}\Omega$	-	0.05	0.1	mA

# **DYNAMIC CHARACTERISTICS**

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	$V_{DM}$ = 67% $V_{DRM(max)}$ ; $T_j$ = 125 °C; exponential waveform; $R_{GK}$ = 1 kΩ	500	800	-	V/μs
t <sub>gt</sub>	Gate controlled turn-on time	$I_{TM} = 2 \text{ A}; V_D = V_{DRM(max)}; I_G = 10 \text{ mA}; $ $dI_G/dt = 0.1 \text{ A}/\mu\text{s}$	-	2	-	μs
t <sub>q</sub>	Circuit commutated turn-off time	$V_D = 67\% V_{DRM(max)}; T_i = 125 °C; I_{TM} = 1.6 A; V_R = 35 V; dI_{TM}/dt = 30 A/\mu s; dV_D/dt = 2 V/\mu s; R_{GK} = 1 k\Omega$	-	100	-	μs

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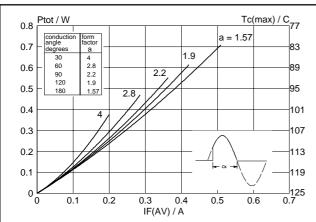


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus average on-state current,  $I_{T(AV)}$ , where  $a = form \ factor = I_{T(RMS)} / I_{T(AV)}$ .

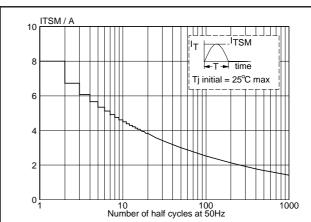


Fig.4. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

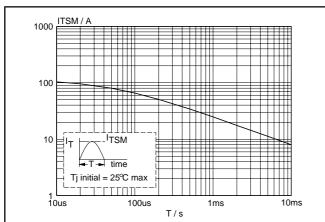


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $\dot{t}_p \leq 10$ ms.

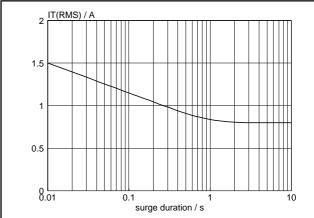


Fig.5. Maximum permissible repetitive rms on-state current I<sub>T(RMS)</sub>, versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{lead} \le 83$ °C.

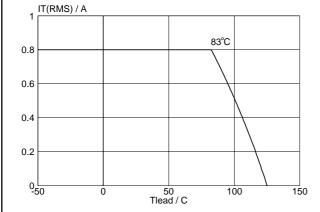


Fig.3. Maximum permissible rms current  $I_{\text{T(RMS)}}$  , versus lead temperature,  $T_{\text{lead}}$ .

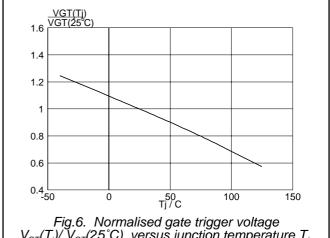
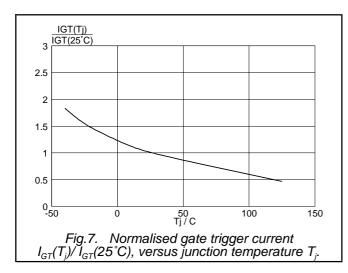


Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$ , versus junction temperature  $T_j$ .

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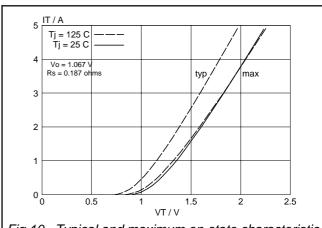
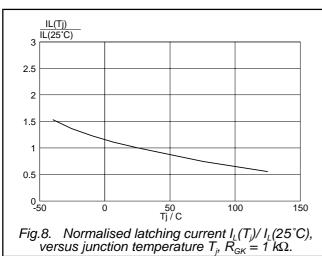


Fig.10. Typical and maximum on-state characteristic.



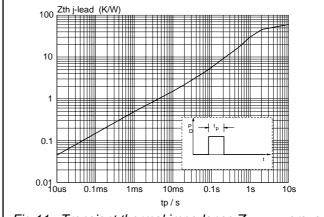


Fig.11. Transient thermal impedance  $Z_{th j-lead}$ , versus pulse width  $t_p$ .

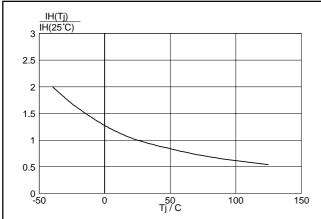


Fig.9. Normalised holding current  $I_H(T_j)/I_H(25^{\circ}C)$ , versus junction temperature  $T_j$ ,  $R_{GK}=1$  k $\Omega$ .

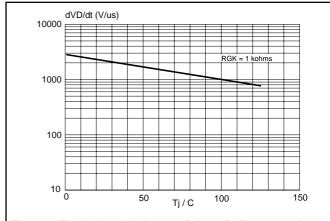
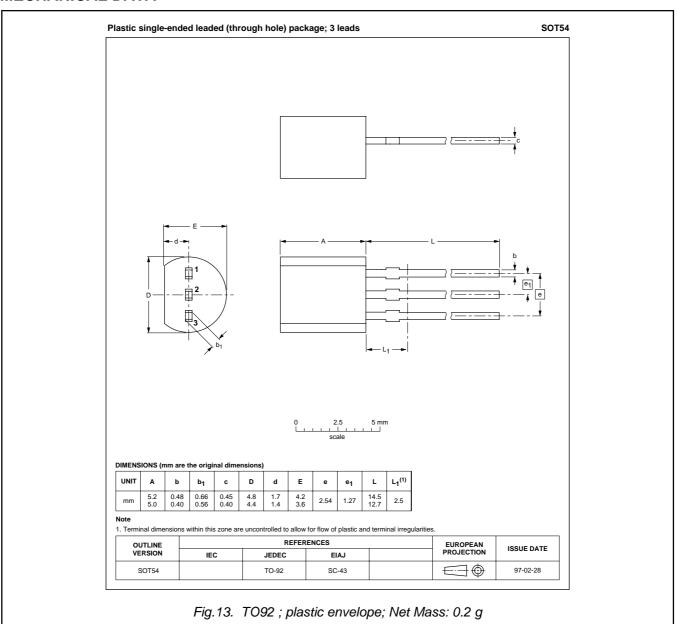


Fig. 12. Typical, critical rate of rise of off-state voltage,  $dV_D/dt$  versus junction temperature  $T_j$ .

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## **MECHANICAL DATA**



## **Notes**

1. Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Thyristors logic level

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### **DEFINITIONS**

DATA SHEET STATUS					
DATA SHEET STATUS <sup>2</sup>	PRODUCT STATUS <sup>3</sup>	DEFINITIONS			
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice			
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product			
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A			

#### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

### Application information

Where application information is given, it is advisory and does not form part of the specification.

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<sup>2</sup> Please consult the most recently issued datasheet before initiating or completing a design.

**<sup>3</sup>** The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.